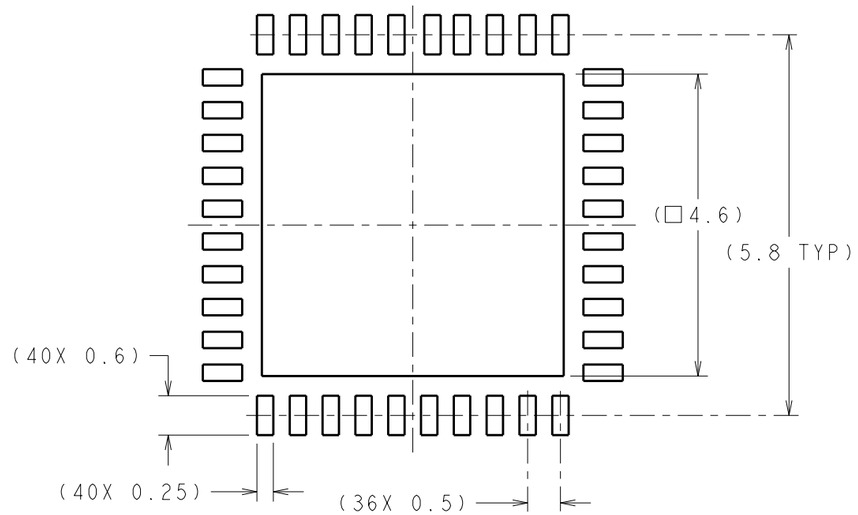
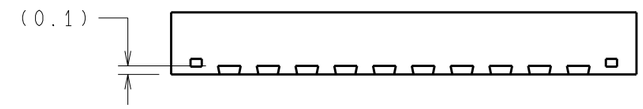
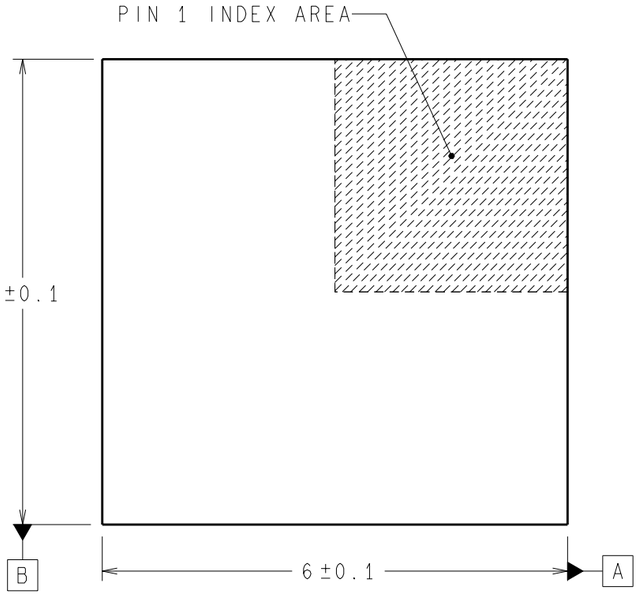
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1345	02/05/2004	TL/AT
B	PAD WIDTH ON LAND PATT WAS 0.3	1392	03/19/2004	TL/AT

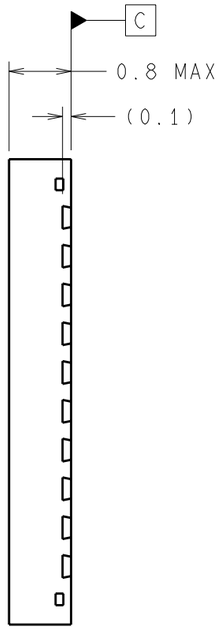


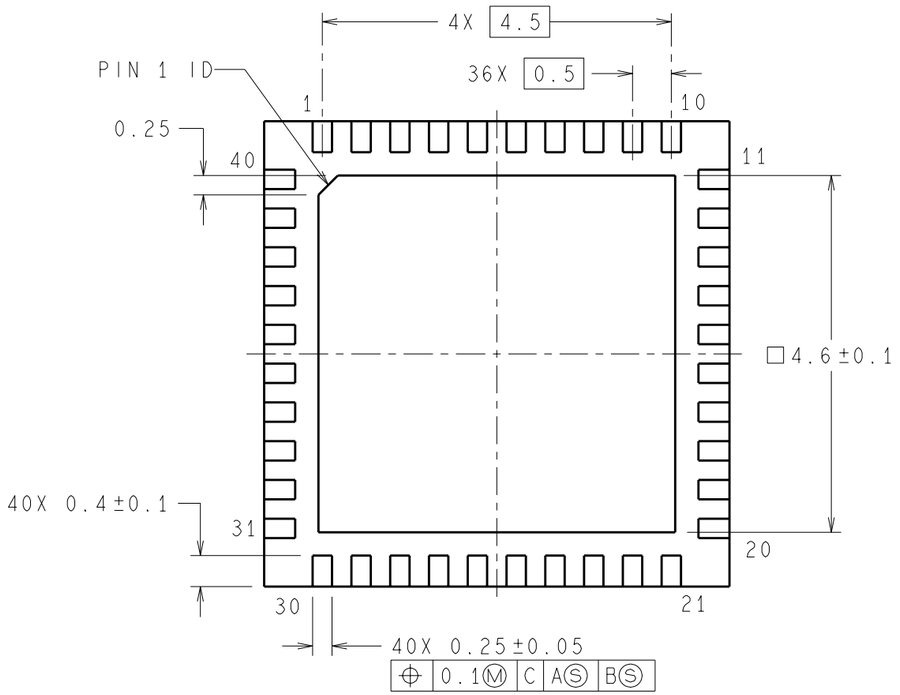
RECOMMENDED LAND PATTERN

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY









NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
3. NO JEDEC REGISTRATION AS OF MARCH 2004.

APPROVALS	DATE
DRAWN T. LEQUANG	02/05/2004
DFTG. CHK. MARTA SUCHY	03/19/2004
ENGR. CHK. ANNY TU	03/19/2004

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, QUAD, 6x6x0.8mm BODY, 40 LD 0.5mm PITCH, NO PULLBACK

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-SQA40A	B

FORMERLY: N/A